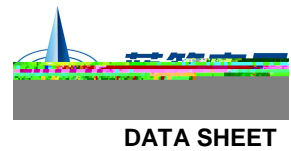




**S8KC~S8MC**  
Rev. B Feb.-2021



800~1000V

8.0A SMC

Surface Mount General Purpose Silicon Rectifier, Reverse Voltage: 800 to 1000 V, Forward Current:8.0A ,SMC package.

RoHS 2011/65/EU

Glass Passivated Chip Junction,Lead free in comply

参数 Parameter	符号 Symbol	数值 Ratio		单位 Unit
		S8KC		
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	800		V
Maximum RMS voltage	$V_{RMS}$	560		V
Maximum DC Blocking Voltage	$V_{DC}$	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$		8.0	A

.0.7 623TD J ET q,r 9.8

/ Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

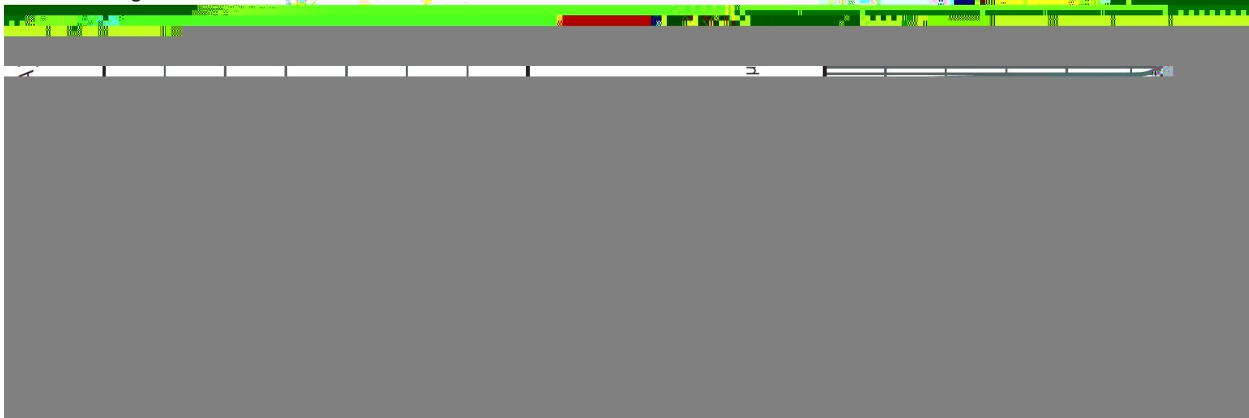


Fig.2 Typical Reverse Characteristics

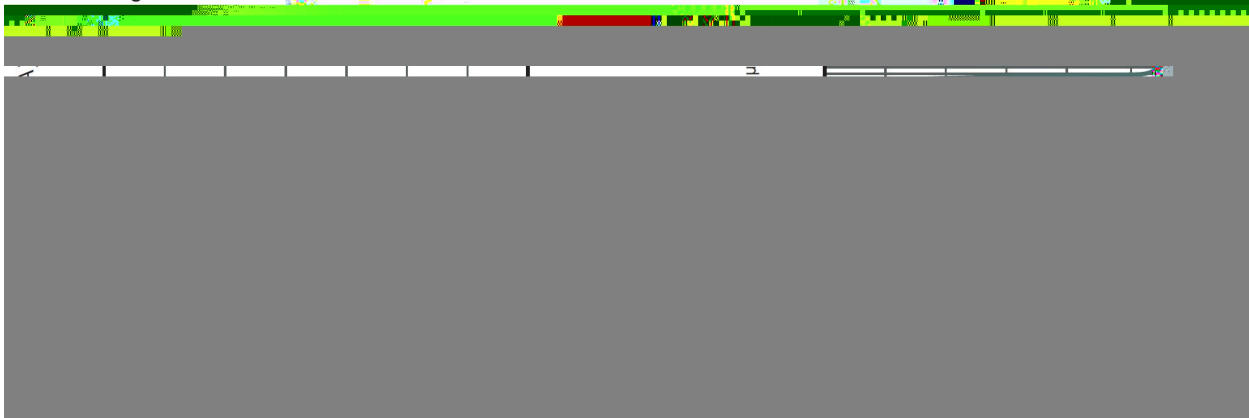
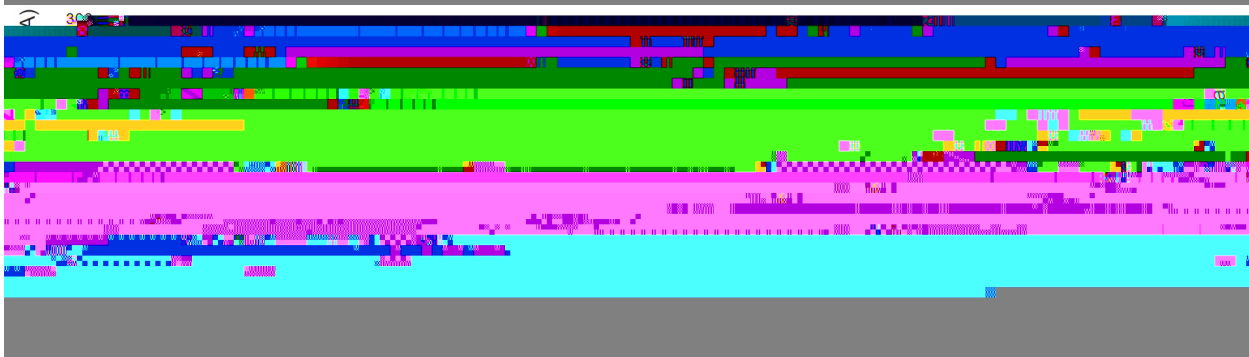
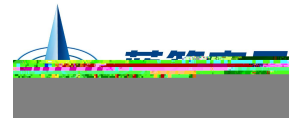


Fig.3 Typical Forward Characteristic



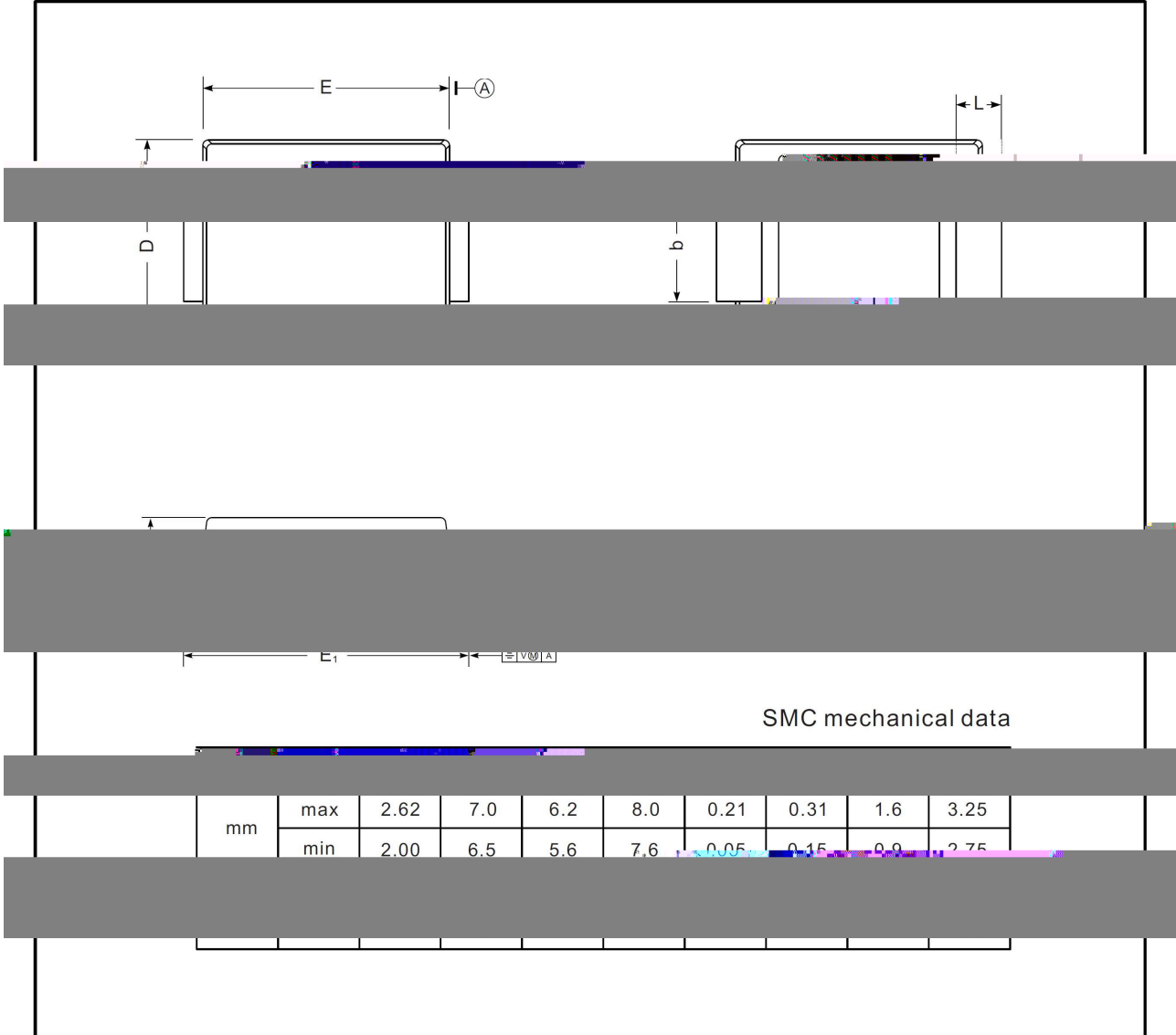
Fig.4 Typical Junction Capacitance





**/ Package Dimensions**

**SMC**



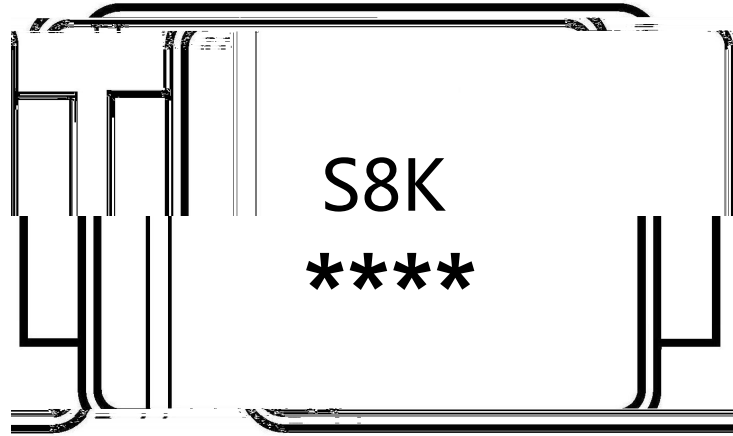
**SMC mechanical data**

	mm	max	2.62	7.0	6.2	8.0	0.21	0.31	1.6	3.25
		min	2.00	6.5	5.6	7.6	0.05	0.15	0.9	2.75

# Marking

Type number	Marking code
S8KC	S8K

/ Marking Instructions



S8K

\*\*\*\*

1 \*

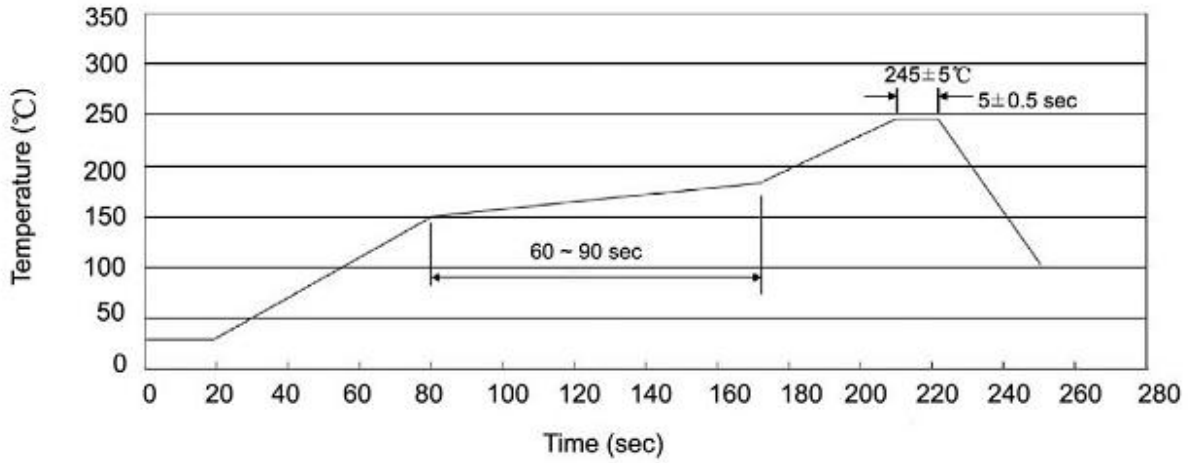
3 \*

Note:

S8K Product Type Code

\*\*\*\* Lot No. Code The 1st \* means:YM Code The last 3 \* means:little Lot No Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |       |           |   |
|---|-------|-----|-------|-----------|---|
| 1 | 150   | 180 | 60    | 90sec;    | 1. Preheating: 150~180°C, Time: 60~90sec.   |
| 2 | 245±5 |     | 5±0.5 | sec;      | 2. Peak Temp.: 245±5°C, Duration: 5±0.5sec. |
| 3 |       |     | 2     | 10°C/sec. | 3. Cooling Speed: 2~10°C/sec.               |

/ Resistance to Soldering Heat Test Conditions

260±5°C      10±1 sec.      Temp.: 260±5°C      Time: 10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm <sup>3</sup> )		
	只卷盘	卷盘盒	只盒	盒箱	只箱			
SMC	3000	2	6000	6	36000	13" x16	337X337X49	380X335X366

/ Notices